

Vishay Siliconix

N-Channel 40 V (D-S) MOSFET

PRODU	CT SUMMARY		
V _{DS} (V)	R _{DS(on)} (Ω) Max.	I _D (A) a, g	Q _g (Typ.)
40	0.00235 at V _{GS} = 10 V	60	32 nC
40	0.00320 at V _{GS} = 4.5 V	60	32 110

PowerPAK® SO-8L Single O Top View Bottom View

Ordering Information:

SiJA54DP-T1-GE3 (lead (Pb)-free and halogen-free)

FEATURES

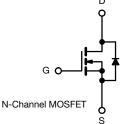
- TrenchFET® Gen IV power MOSFET
- Tuned for the lowest R_{DS}-Q_{oss} FOM
- 100 % Rq and UIS tested
- Q_{gd} / Q_{gs} ratio < 1 optimizes switching characteristics





APPLICATIONS

- Synchronous rectification
- ORing
- High power density DC/DC
- VRMs and embedded DC/DC
- DC/AC inverters
- · Load switch



ABSOLUTE MAXIMUM RATINGS ($T_A = 25 ^{\circ}C$, unless	otherwise note	d)	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	40	V
Gate-Source Voltage		V_{GS}	+20, -16	V
	T _C = 25 °C		60 ^g	
Continuous Proin Current (T - 150 °C)	T _C = 70 °C		60 g	
Continuous Drain Current (T _J = 150 °C)	tt $(T_J = 150 ^{\circ}\text{C})$ $T_A = 25 ^{\circ}\text{C}$ I_D $32.2^{\text{b, c}}$			
	T _A = 70 °C		25.7 ^{b, c}	A
Pulsed Drain Current (t = 100 μs)		I _{DM}	150	
Continuous Courses Drain Diada Current	T _C = 25 °C 33.3			
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	4 b, c	
Single Pulse Avalanche Current		I _{AS}	30	
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	45	mJ
	T _C = 25 °C		36.7	
Marian and Danier Dispiration	T _C = 70 °C		23.5	14/
Maximum Power Dissipation	T _A = 25 °C	P _D	4.4 b, c	— w
	T _A = 70 °C		2.8 b, c	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C
Soldering Recommendations (Peak Temperature) d, e			260	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient b, f	t ≤ 10 s	R _{thJA}	24	28	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	2.5	3.4	C/VV

Notes

- a. $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 10 s
- d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- f. Maximum under steady state conditions is 70 °C/W.
- g. Package limited.



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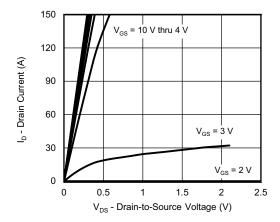
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40	-	-	V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	ΔV _{DS} /T _J		24	-	\//00	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 HA		-5.2	-	mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.1	-	2.4	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = +20 \text{ V}, -16 \text{ V}$	-	-	± 100	nA	
Zoro Coto Voltago Drain Current		V _{DS} = 40 V, V _{GS} = 0 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10	μA	
On-State Drain Current a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30	-	-	Α	
Drain-Source On-State Resistance a	Б	V _{GS} = 10 V, I _D = 15 A	-	0.00195	0.00235	35	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	-	0.00265	0.00320	Ω	
Forward Transconductance a	9 _{fs}	V _{DS} = 10 V, I _D = 15 A	-	106	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	5300	-	pF	
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	707	-		
Reverse Transfer Capacitance	C _{rss}		-	105	-		
Total Cata Charge	Qg	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	69	104		
Total Gate Charge			-	32	48	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	-	13.5	-		
Gate-Drain Charge	Q_{gd}		-	6.9	-		
Output Charge	Q _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	-	30.5	46		
Gate Resistance	Rg	f = 1 MHz	0.4	1.1	2.0	Ω	
Turn-On Delay Time	t _{d(on)}		-	8	16		
Rise Time	t _r	$V_{DD} = 20 \text{ V}, \text{ R}_{L} = 2 \Omega$	-	8	16	=	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 10~A,~V_{GEN}=10~V,~R_g=1~\Omega$	-	28	56		
Fall Time	t _f		-	7	14		
Turn-On Delay Time	t _{d(on)}		-	24	48	ns	
Rise Time	t _r	$V_{DD} = 20 \text{ V}, \text{ R}_{L} = 2 \Omega$	-	69	138		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 10$ A, $V_{GEN}=4.5$ V, $R_g=1$ Ω	-	23	46		
Fall Time	t _f		-	10	20		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	Is	T _C = 25 °C	-	-	33.3	А	
Pulse Diode Forward Current (t = 100 μs)	I _{SM}		-	-	150		
Body Diode Voltage	V_{SD}	I _S = 5 A	-	0.72	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}		-	44	88	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 10 A 41/44 100 A / - T 05 00	-	58	116	nC	
Reverse Recovery Fall Time	ta	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$	-	29	-		
Reverse Recovery Rise Time	t _b		-	15	-	ns	

Notes

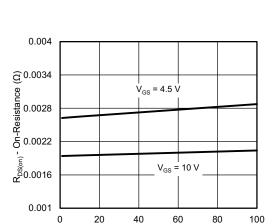
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



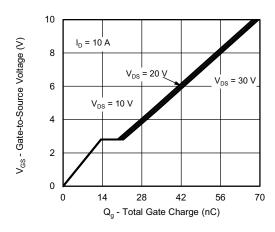


Output Characteristics

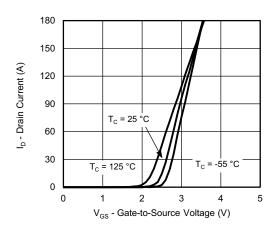


On-Resistance vs. Drain Current

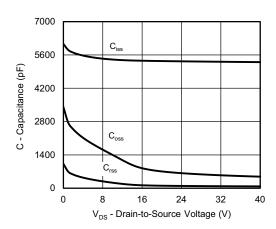
I_D - Drain Current (A)



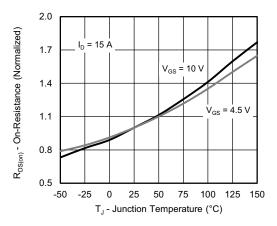
Gate Charge



Transfer Characteristics

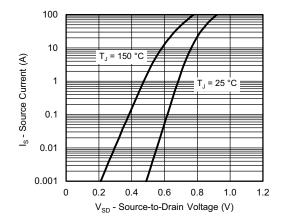


Capacitance

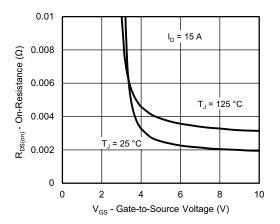


On-Resistance vs. Junction Temperature

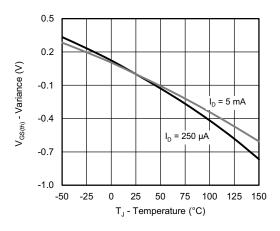




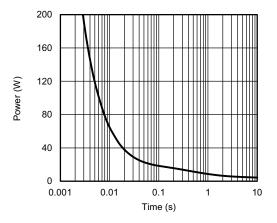
Source-Drain Diode Forward Voltage



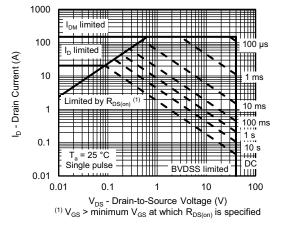
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

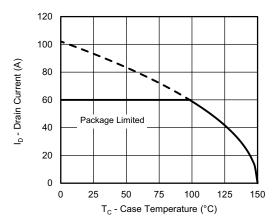


Single Pulse Power, Junction-to-Ambient

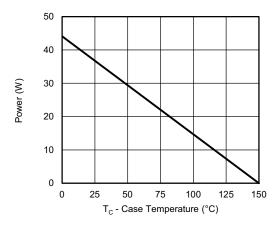


Safe Operating Area, Junction-to-Ambient

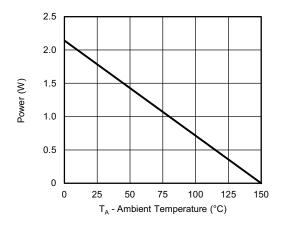




Current Derating a





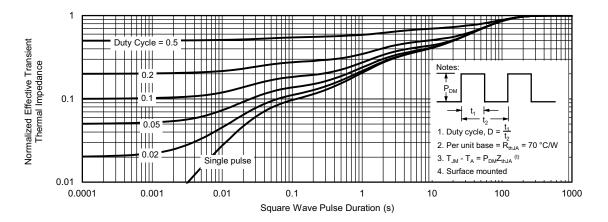


Power, Junction-to-Ambient

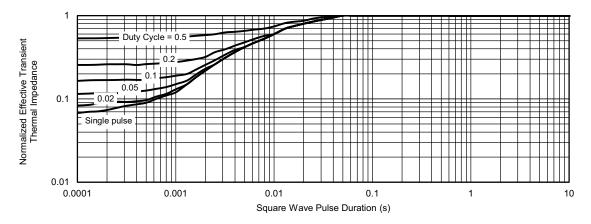
Note

a. The power dissipation P_D is based on T_J (max.) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient

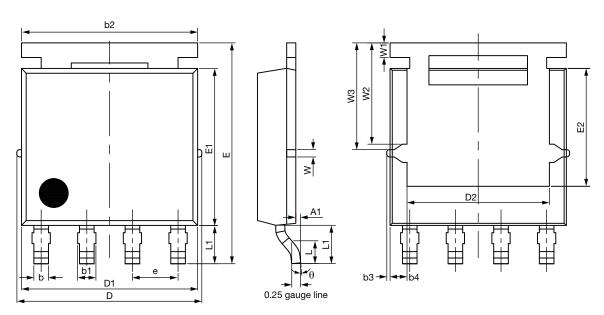


Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?67424.

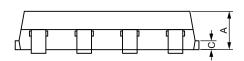
Vishay Siliconix

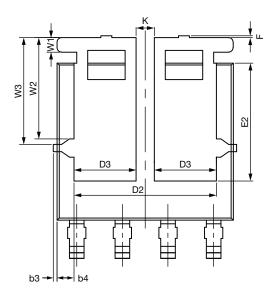
PowerPAK® SO-8L Case Outline for Non-Al Parts



Topside view

Backside view (single)





Backside view (dual)





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D.114		MILLIMETERS			INCHES		
DIM.	MIN. NOM. MAX			MIN.	NOM.	MAX.	
Α	1.00	1.07	1.14	0.039	0.042	0.04	
A1	0.00	-	0.127	0.00	-	0.00	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	3.18	3.28	3.38	0.125	0.129	0.13	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51			0.020		
W	0.23			0.009			
W1	0.41			0.016			
W2	2.82			0.111			
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

ECN: T16-0221-Rev. D, 16-May-16

DWG: 5976

Note

• Millimeters will gover



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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